

#### **Presentation Disclaimer**

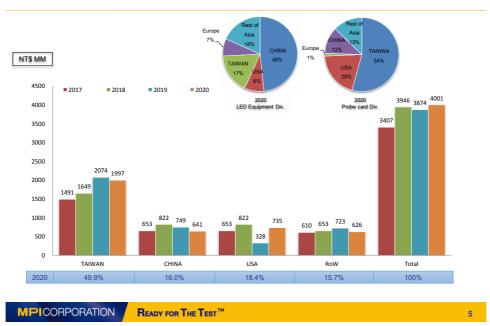
The information herein contains forward-looking statements. We have based these forward-looking statements on our current expectations and projections about future events. Although we believe that these expectations and projections are reasonable, such forward-looking statements are inherently subject to risks, uncertainties and assumptions about us, including, among other things: the intensely competitive Semi-conductor, and LED industries and markets; Cyclical nature of the semiconductor industry; Risks associated with global business activities; General economic and political conditions. All financial figures discussed herein are prepared pursuant to IFRS. All audited figures will be publicly announced upon the completion of our audited process.

# Company at a Glance



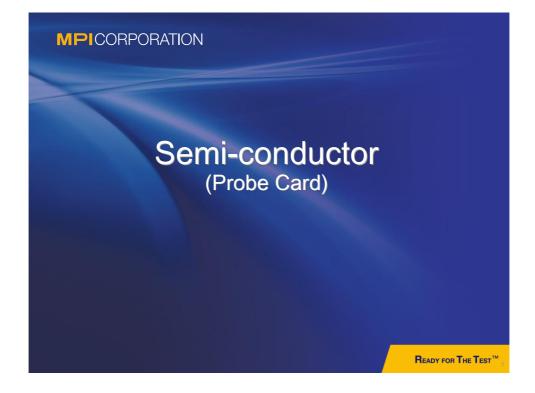
#### **Business Portfolio**



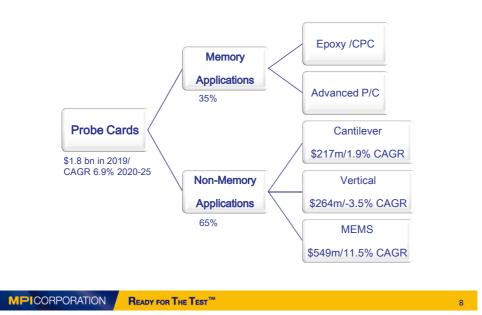


#### Net Sales by Geographic





## **Global Probe Card Market Update**



# Top 10 Probe Card Vendors (2015-2020)

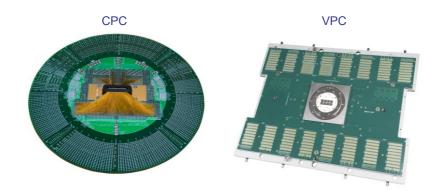
(Rank)		2015	2016	2017	2018	2019	2020
FormFactor, Inc.	USA	1	1	1	1	1	1
Micronics Japan Co., Ltd.	Japan	2	2	2	3	3	3
Technoprobe	Italy	3	3	3	2	2	2
Japan Electronic Materials	Japan	4	4	4	4	4	4
MPI Corporation	Taiwan	5	5	5	5	5	5
SV TCL	Singapore	7	6	6	6	6	7
Microfriend	Korea	10	7	7	10	10	10
Korea Instrument	Korea	9	8	8	7	8	6
Cascade Microtech	USA	6	9	-	-	-	-
FEINMETALL	Germany	11	10	11	12	11	14

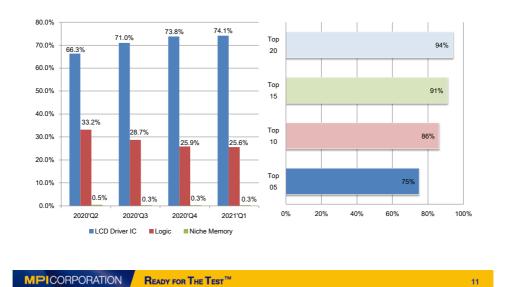
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#### **CPC & VPC**





#### Product Mix of CPC (Cantilever)

## **CPC Pin-Shipment**

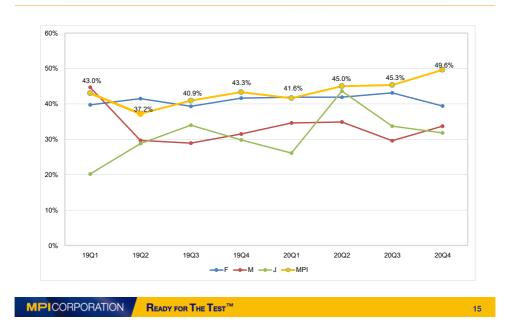




#### **VPC Pin-Shipment**

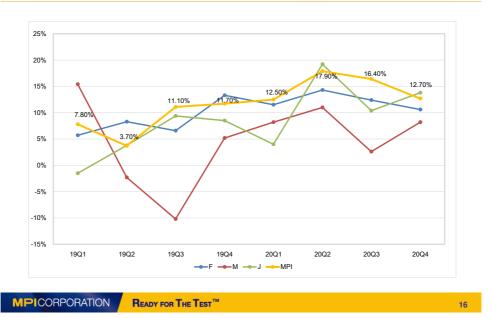
#### CPC and VPC Yearly Status

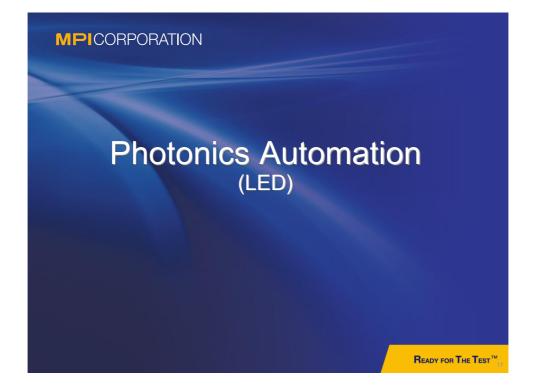




#### **Gross Margin Between Global Peers**

#### **Operating Margin Between Global Peers**





## Photonics Automation (PA) Overview





#### Main Product Line



Package Level Chip Scale Package (CSP) Foil to Foll (FTF) Inspection System

Chip after dicing Chip after sorting



Package Probing

Panel Bottom probing Single package



Package Testing From low to high power







LED Package Probing

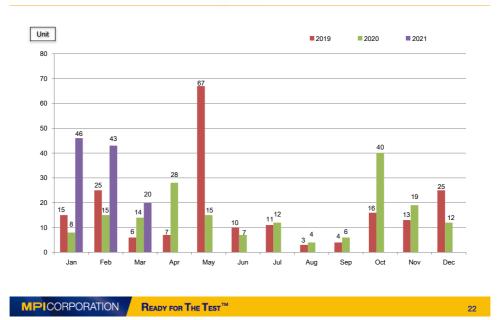
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#### 855 699 195 P,9000 P7602F P80C4 NEW A2000P A3000 NEW M76FP M76V M60D MPICORPORATION READY FOR THE TEST<sup>™</sup> 21

#### Wafer Technology Migration

# 2021 Shipment





#### Thermal



- Addressable Market Size: roughly USD\$30m
- Applied Industries: Telecom / Automotive/Industrial, industrial and semi industries

http://www.mpi-thermal.com/media/

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- Market size: roughly USD\$400m
- Industry: Foundry/IC design houses' engineering stage process











# **Balance Sheet Highlight**

202	20	2019		
1,445	16%	1103	14%	
3,735	42%	3,362	41%	
8,976	100%	8,178	100%	
763		142		
5,648	63%	4,379	54%	
844		489		
	1,445 3,735 8,976 763 5,648 844	3,735 42%   8,976 100%   763 5,648	1,445 16% 1103   3,735 42% 3,362   8,976 100% 8,178   763 142   5,648 63% 4,379   844 489	

\*EBITDA=operating income + depreciation & amortization expenses

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#### **Income Statement**

NT\$1,000	2020		2019		
Net Sales	5,925,601	100%	5,515,200	100%	
Cost of Goods Sold	3,340,036	56%	3,286,299	59%	
Gross Profit	2,585,565	44%	2,228,901	41%	
Operating Expense	1,725,536	29%	1,751,653	32%	
Operating Income	860,029	15%	477,248	9%	
Investment Income & Others	-15,314		11,783		
Net Income (before tax)	714,221	12%	427,984	8%	
EPS	8.41		5.36		

#### Net Sales NT\$ 1,000

